

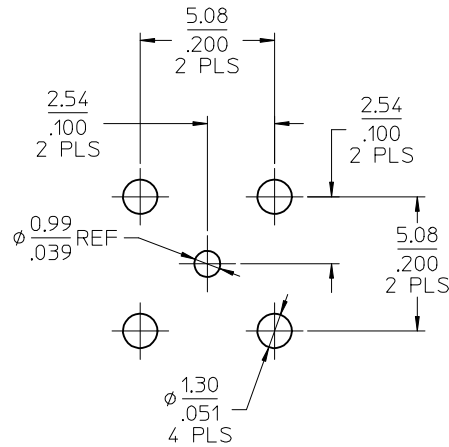
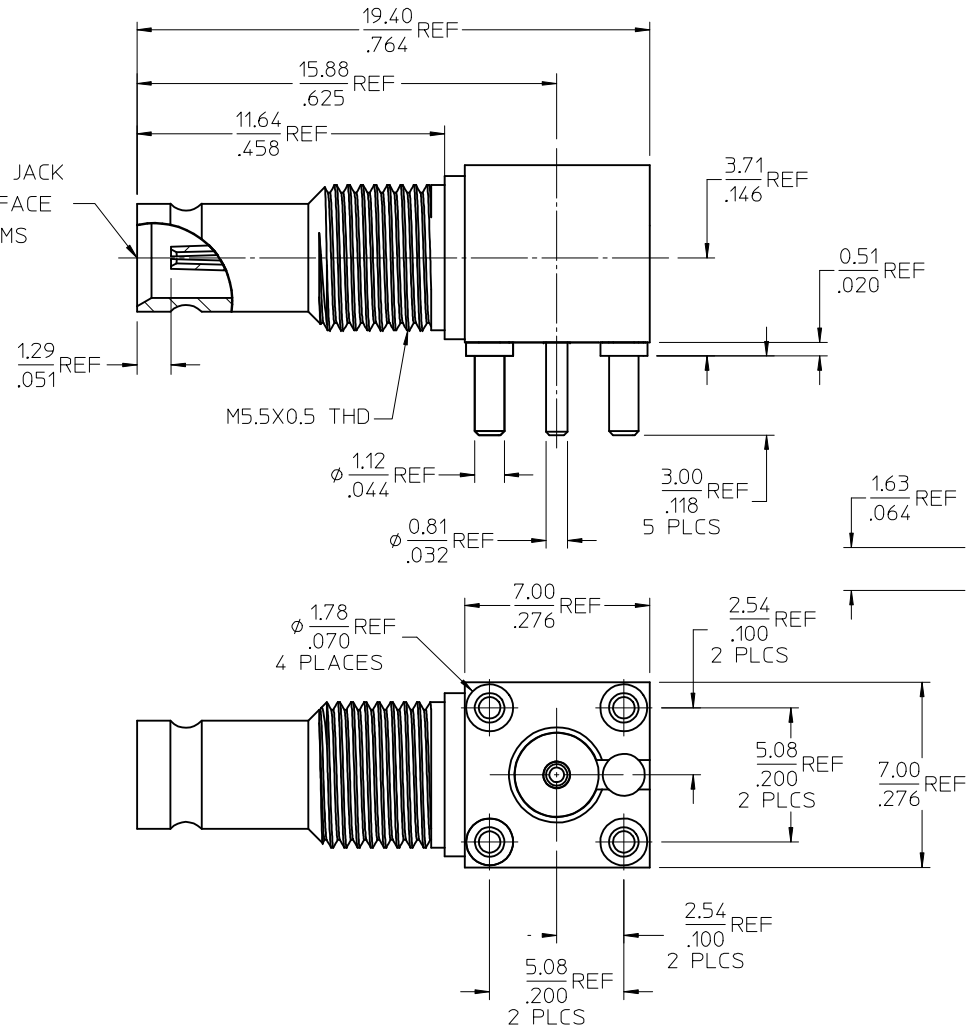
MATERIALS AND FINISHES

BODY, PIN, RETAINING RING, NUT: BRASS
PLATED: SEE TABLE

CONTACT: PHOSPHOR BRONZE
PLATED: GOLD (10μ-in MIN) OVER
NICKEL (100μ-in MIN)

INSULATOR: PTFE

1.0/2.3 JACK
INTERFACE
50 OHMS



RECOMMENDED HOLE LAYOUT

PS-89675-3450	PRODUCT SPECIFICATION
CECC 22 230	INTERFACE
SPECIFICATION	DESCRIPTION

73174-0411	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)
73174-0410	NICKEL (70μ-in MIN)
PART NO.	PLATING

CHG: UPDATE VIEWS
FOR BODY AND POST
CHANGES. ADD
PLATING THICKNESS
TO MATERIAL AND
FINISH BLOCK/TABLE.
ADD Ø1.78 4 PLACES
DIM. ADD CUTAWAY
VIEW AND 129 REF
DIM. DEL MACHINING
NOTE.

EC NO: URF2017-0075
2016/08/09
DRWN: MEIER
2016/08/10
CHKD: SSS
2016/08/16
APPR: ROBERTSON

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .005	± .0004
3 PLACES	± .003	± .0002
2 PLACES	± .002	± .0001
1 PLACE	± .001	± .00005

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM/IN

DRAWN BY	DATE
SSS	2004/03/02
CHECKED BY	DATE
TEF	2004/03/02
APPROVED BY	DATE
GMH	2004/03/02

MATERIAL NO.
SEE TABLE

SCALE
DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

TITLE
1.0/2.3 JACK, R/A PCB
50 OHMS, EWR-2361
1.0/2.3-J/PCB

MOLEX INCORPORATED

DOCUMENT NO.
SD-73174-041

SHEET NO.
1 OF 1